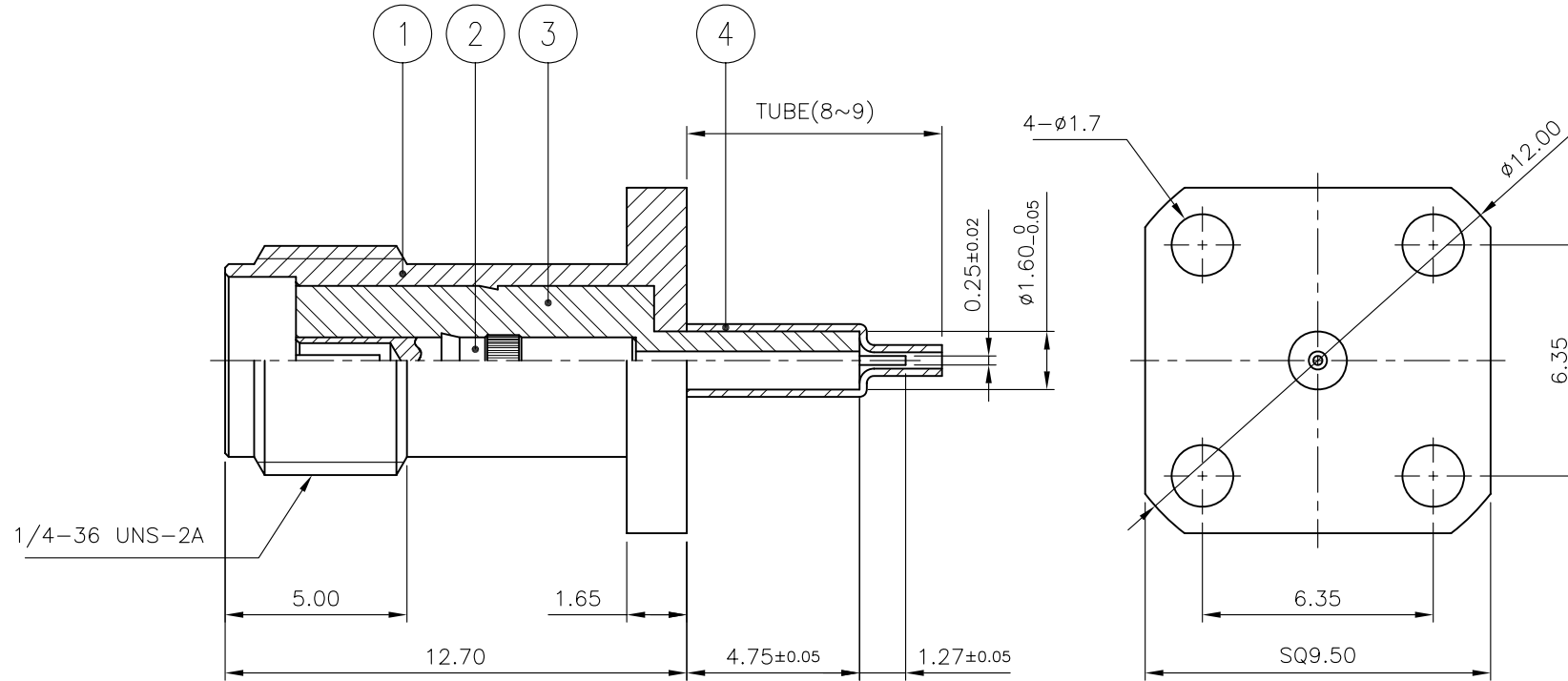


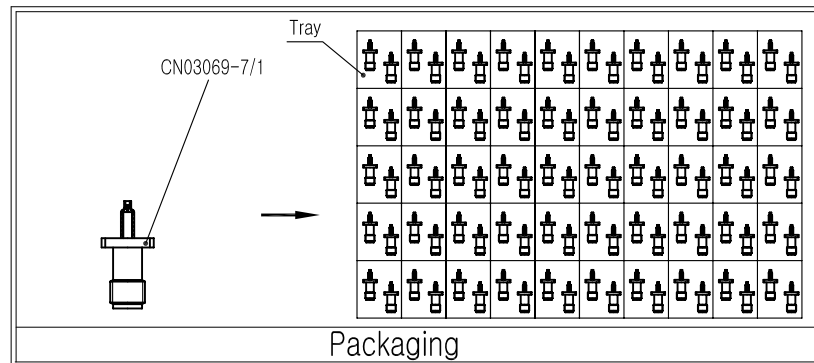
REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	M.H.SONG	I.C.KIM	2013.09.05.



주 기

1. 포장 사양 - 완제품 조립후 Shrink tube를 절연체 위로 수축하여,
개별 비닐 포장후 Tray에 넣는다.

※※ 2. 내부 및 외부 비닐 포장, BOX 포장시 KJ 회사로고 없는 것으로 작업 할 것.



4	SHRINK TUBE	1			ATU00052-N/1(Ø2-Black)
3	INSULATOR	1	TEFLON		DIN02240-N/1
2	CONTACT	1	BeCu	Gold Plate	DCT02919-5/1
1	BODY	1	SUS	Passivate	DBD03427-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2013. 09. 05.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY	E.H.KIM	KJ COMTECH CO.,LTD. TITLE SMA50 SOLDER END JS-4H
		DRAWN BY	M.H.SONG	
FINISH		SCALE	4/1	A4 DWG NO. CN03069-7/1 REVISION I R SHEET 1 of 1
		UNIT	mm	